

## 1. General description

Planar passivated Silicon Controlled Rectifier (SCR) module in TO-240AA for use in applications requiring high blocking voltage capability, high inrush current capability and high thermal cycling performance.

## 2. Features and benefits

- High blocking voltage capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- Package meets UL certification
- Package is RoHS compliant
- Industry standard outline
- Soldering pins for PCB mounting
- Copper base plate
- Cathode Kelvin contacts provided
- UL1557 certified (Document number E346397)

## 3. Applications

- Softstart AC motor control
- DC Motor control
- AC power control
- Power converter
- Temperature control
- Lighting control

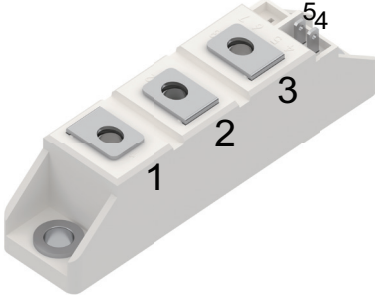
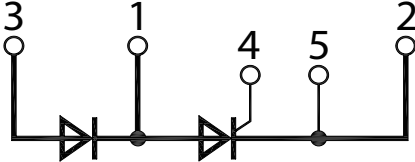
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V <sub>DRM</sub>	repetitive peak forward voltage			1600			V
V <sub>RRM</sub>	repetitive peak reverse voltage			1600			V
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave		125			A
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse		80			A
I <sub>TSM</sub> /I <sub>FSM</sub>	non-repetitive peak on-state current	half sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 10 ms		1700			A
		half sine wave; T <sub>j(init)</sub> = 150 °C; t <sub>p</sub> = 10 ms		1400			A
		half sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 8.3 ms		1850			A
		half sine wave; T <sub>j(init)</sub> = 150 °C; t <sub>p</sub> = 8.3 ms		1500			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C		30	-	100	mA
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C		-	0.70	1.20	V
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 80 A; T <sub>J</sub> = 25 °C		-	-	1.29	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 80 A; T <sub>J</sub> = 25 °C		-	-	1.29	V

5. Pinning information

Table 2. Pinning information

Simplified outline	Graphic symbol
	

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WHMH80T16	TO-240AA	WHMH80T16T	Tray	12	WeEnPACK-20mmPHB-D	18-Apr-2024

7. Marking

Table 4. Marking codes

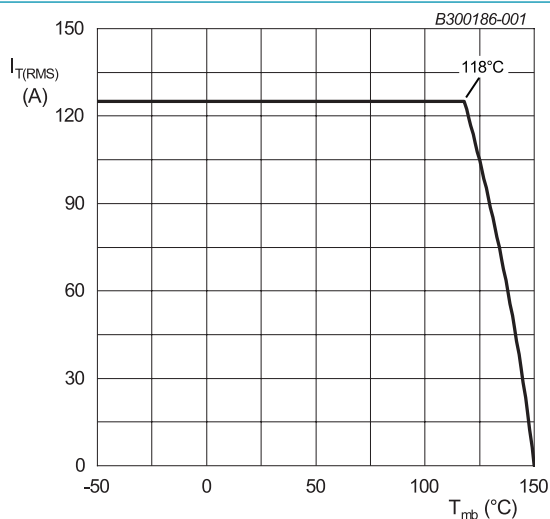
Type number	Marking codes
WHMH80T16	WHMH80T16

## 8. Limiting values

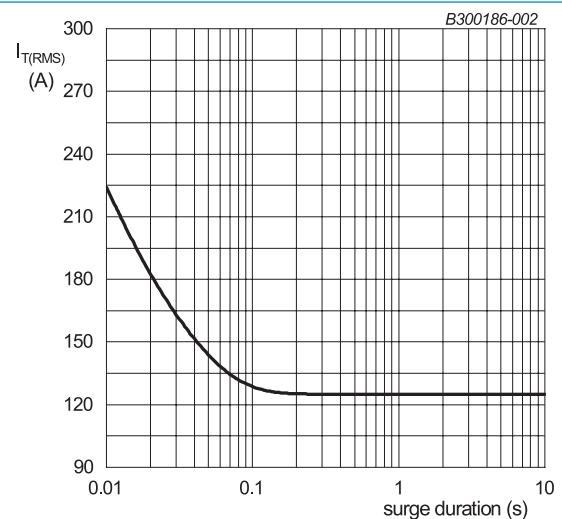
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{DRM}$	repetitive peak forward voltage			1600	V
$V_{RRM}$	repetitive peak reverse voltage			1600	V
$I_{T(RMS)}$	RMS on-state current	half sine wave		125	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse		80	A
$I_{TSM}/I_{FSM}$	non-repetitive peak onstate current	half sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$		1700	A
		half sine wave; $T_{J(init)} = 150\text{ °C}$ ; $t_p = 10\text{ ms}$		1400	A
		half sine wave; $T_{J(init)} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$		1850	A
		half sine wave; $T_{J(init)} = 150\text{ °C}$ ; $t_p = 8.3\text{ ms}$		1500	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse		12.8	kA <sup>2</sup> s
$di_T/dt$	rate of rise of on-state current	$I_G = 200\text{ mA}$ ; $T_J = 150\text{ °C}$		200	A/ $\mu$ s
$I_{GM}$	peak gate current			10	A
$V_{RGM}$	peak reverse gate voltage			5	V
$P_{GM}$	peak gate power			20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
$T_{vj}$	virtual junction temperature			-40 to 150	°C
$T_{op}$	operation temperature			-40 to 130	°C
$T_{stg}$	storage temperature			-40 to 130	°C



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



**Fig. 2. RMS on-state current as a function of surge duration; maximum values**  
 $f = 50\text{ Hz}$ ;  $T_{mb} = 118\text{ °C}$

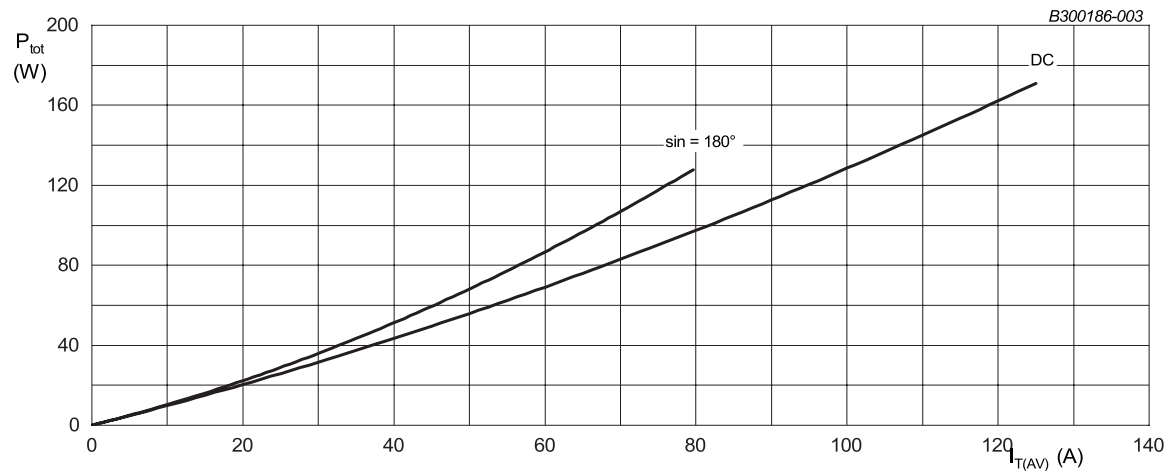
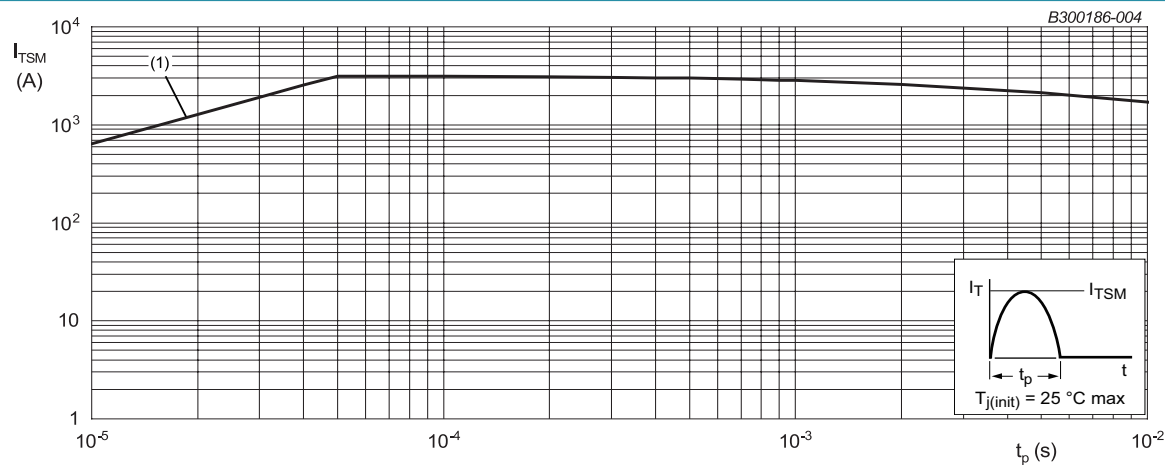


Fig. 3. Total power dissipation as a function of average on-state current; maximum values; per thyristor



$t_p \leq 10\text{ ms}$   
(1)  $di_T/dt$  limit

Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

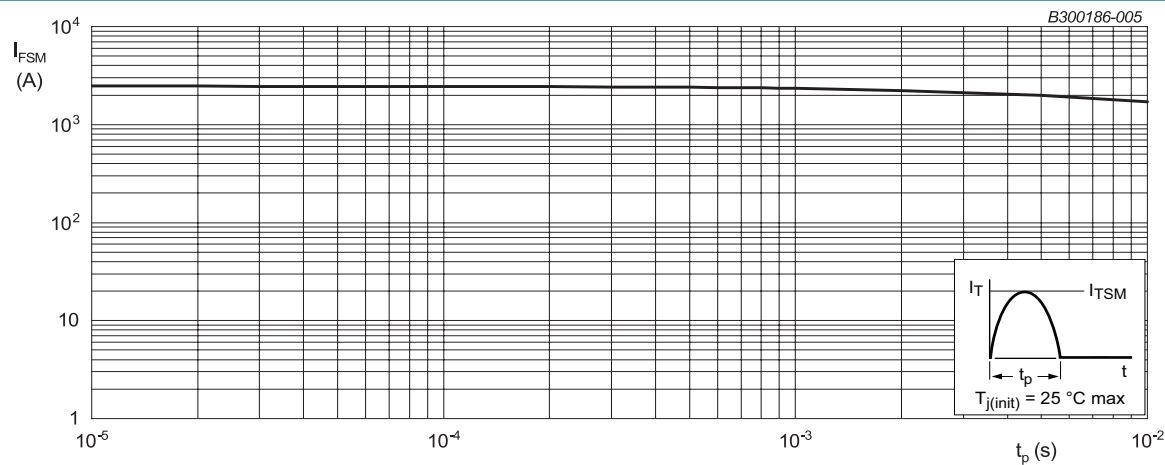


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	per thyristor/diode		-	-	0.25	K/W
		per module		-	-	0.125	K/W
$R_{th(j-h)}$	thermal resistance from junction to heatsink	per thyristor/diode		-	-	0.48	K/W
		per module		-	-	0.24	K/W

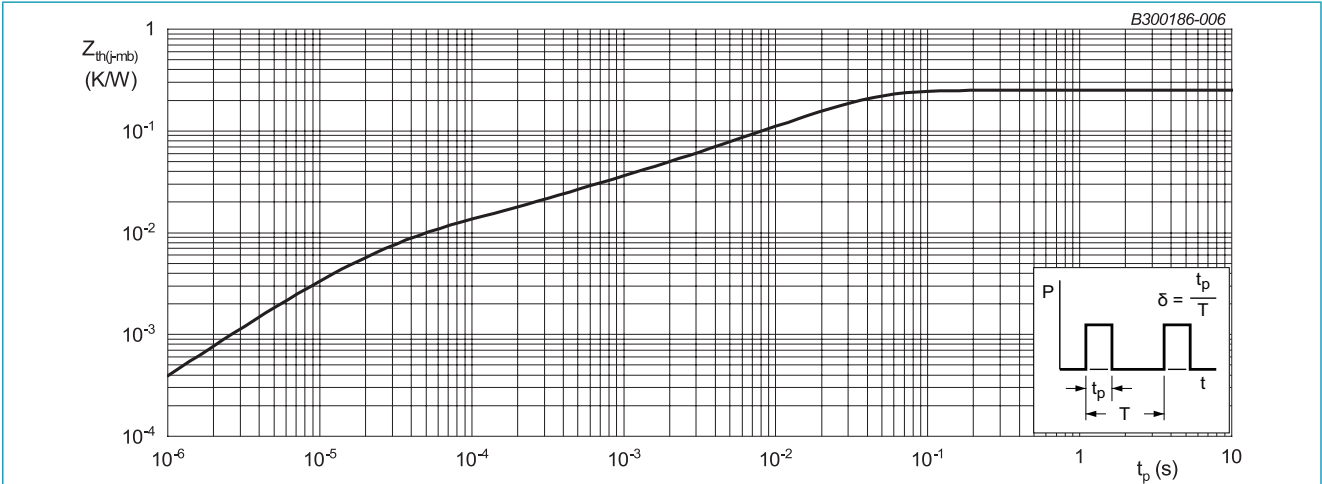


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration; per thyristor

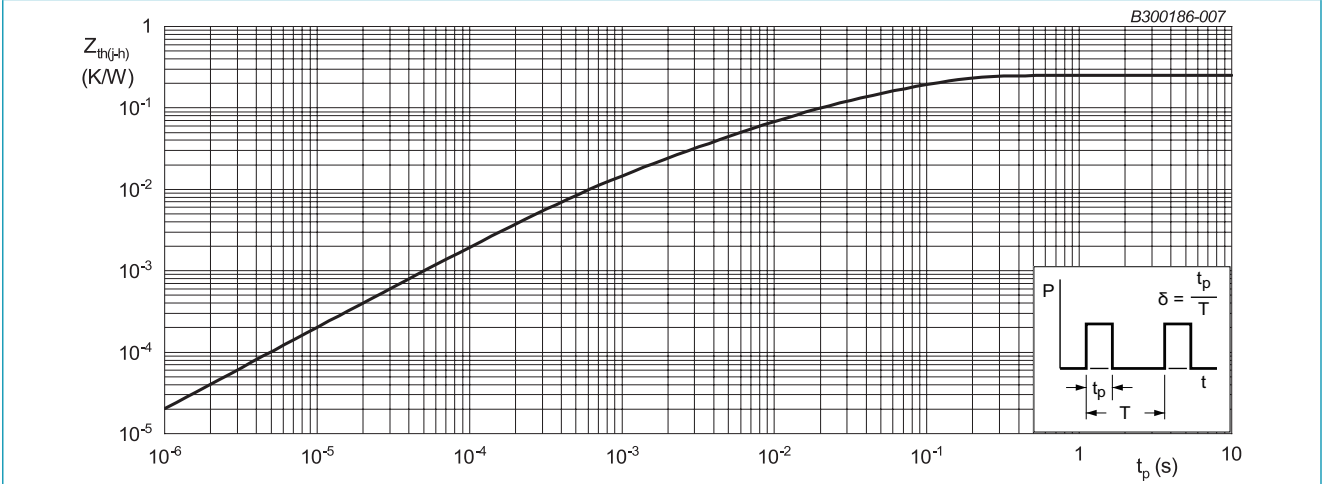


Fig. 7. Transient thermal impedance from junction to mounting base as a function of pulse duration; per diode

10. Package characteristics

Table 7. Isolation characteristics

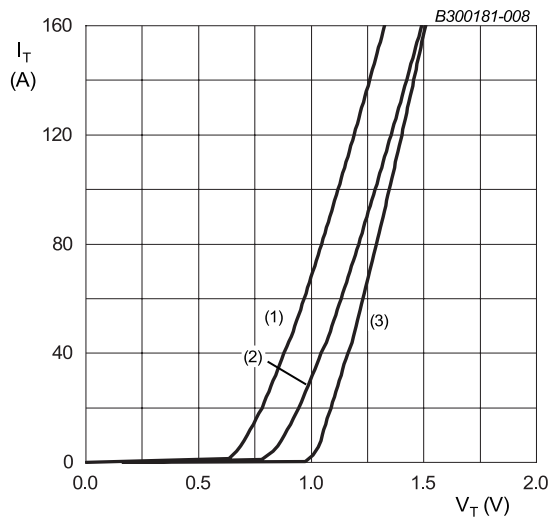
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$V_{isol}$	isolation voltage	50/60 Hz; RMS; $I_{ISOL} \leq 1\text{ mA}$ ; $t = 1\text{ second}$ ; AC		-	-	3600	V
		50/60 Hz; RMS; $I_{ISOL} \leq 1\text{ mA}$ ; $t = 1\text{ minute}$ ; AC		-	-	3000	V

## 11. Characteristics

Table 8. Characteristics

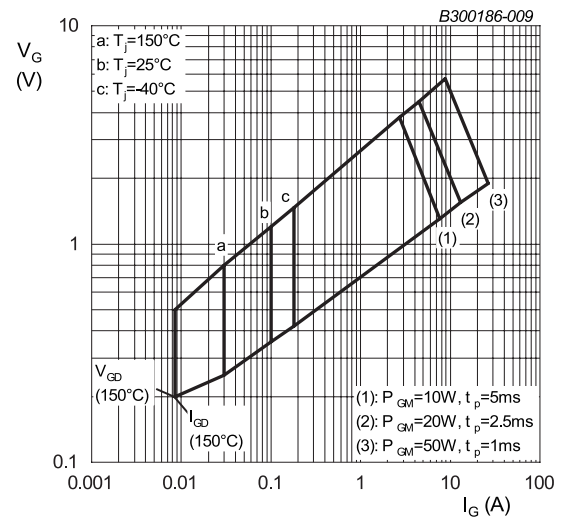
Thyristor							
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C		30	-	100	mA
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C		-	0.70	1.20	V
		V <sub>D</sub> = 2/3 V <sub>DRM</sub> ; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 150 °C		0.25	0.4	-	V
I <sub>GD</sub>	gate non-trigger current	T <sub>J</sub> = 150 °C		-	-	8.5	mA
V <sub>GD</sub>	gate non-trigger voltage	T <sub>J</sub> = 150 °C		-	-	0.2	V
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C		-	-	300	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>J</sub> = 25 °C		-	-	200	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 80 A; T <sub>J</sub> = 25 °C		-	-	1.29	V
V <sub>TO</sub>	threshold voltage	T <sub>J</sub> = 150 °C		-	-	0.952	V
r <sub>T</sub>	slope resistance	T <sub>J</sub> = 150 °C		-	-	3.3	mΩ
I <sub>D</sub>	off-state current	V <sub>D</sub> = 1600 V; T <sub>J</sub> = 25 °C		-	-	100	μA
		V <sub>D</sub> = 1600 V; T <sub>J</sub> = 150 °C		-	-	15	mA
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1600 V; T <sub>J</sub> = 25 °C		-	-	100	μA
		V <sub>R</sub> = 1600 V; T <sub>J</sub> = 150 °C		-	-	15	mA
Dynamic characteristics							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 1072 V; T <sub>J</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit		1500	-	-	V/μs
t <sub>gt</sub>	gate-controlled turn-on time	I <sub>TM</sub> = 40 A; V <sub>D</sub> = 800 V; I <sub>G</sub> = 100 mA; (dI <sub>G</sub> /dt) <sub>M</sub> = 1 A/μs; T <sub>J</sub> = 25 °C		-	2	-	μs
t <sub>q</sub>	commutated turn-off time	I <sub>TM</sub> = 2 A; t <sub>p</sub> = 50 μs; dV/dt = 5 V/μs; dI/dt = 30 A/μs; T <sub>i</sub> = 25 °C		-	150	-	μs

Diode							
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
$V_F$	forward voltage	$I_F = 80\text{ A}; T_J = 25\text{ }^\circ\text{C}$		-	1.05	1.23	V
		$I_F = 80\text{ A}; T_J = 150\text{ }^\circ\text{C}$		-	-	1.12	V
$V_O$	threshold voltage	$T_J = 150\text{ }^\circ\text{C}$		-	-	0.889	V
$R_S$	slope resistance	$T_J = 150\text{ }^\circ\text{C}$		-	-	3.0	mΩ
$I_R$	reverse current	$V_R = 1600\text{ V}; T_J = 25\text{ }^\circ\text{C}$		-	-	100	μA
		$V_R = 1600\text{ V}; T_J = 150\text{ }^\circ\text{C}$		-	-	15	mA

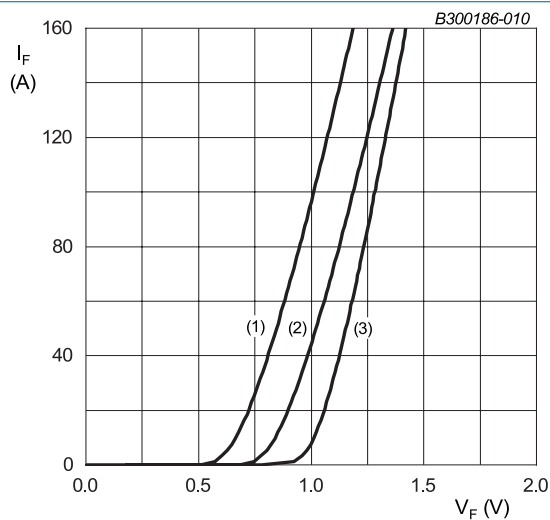


$V_{TO} = 0.952 \text{ V}$ ;  $r_T = 0.0033 \Omega$   
 (1)  $T_J = 150^\circ\text{C}$ ; typical values  
 (2)  $T_J = 150^\circ\text{C}$ ; maximum values  
 (3)  $T_J = 25^\circ\text{C}$ ; maximum values

**Fig. 8. Thyristor on-state current as a function of on-state voltage**



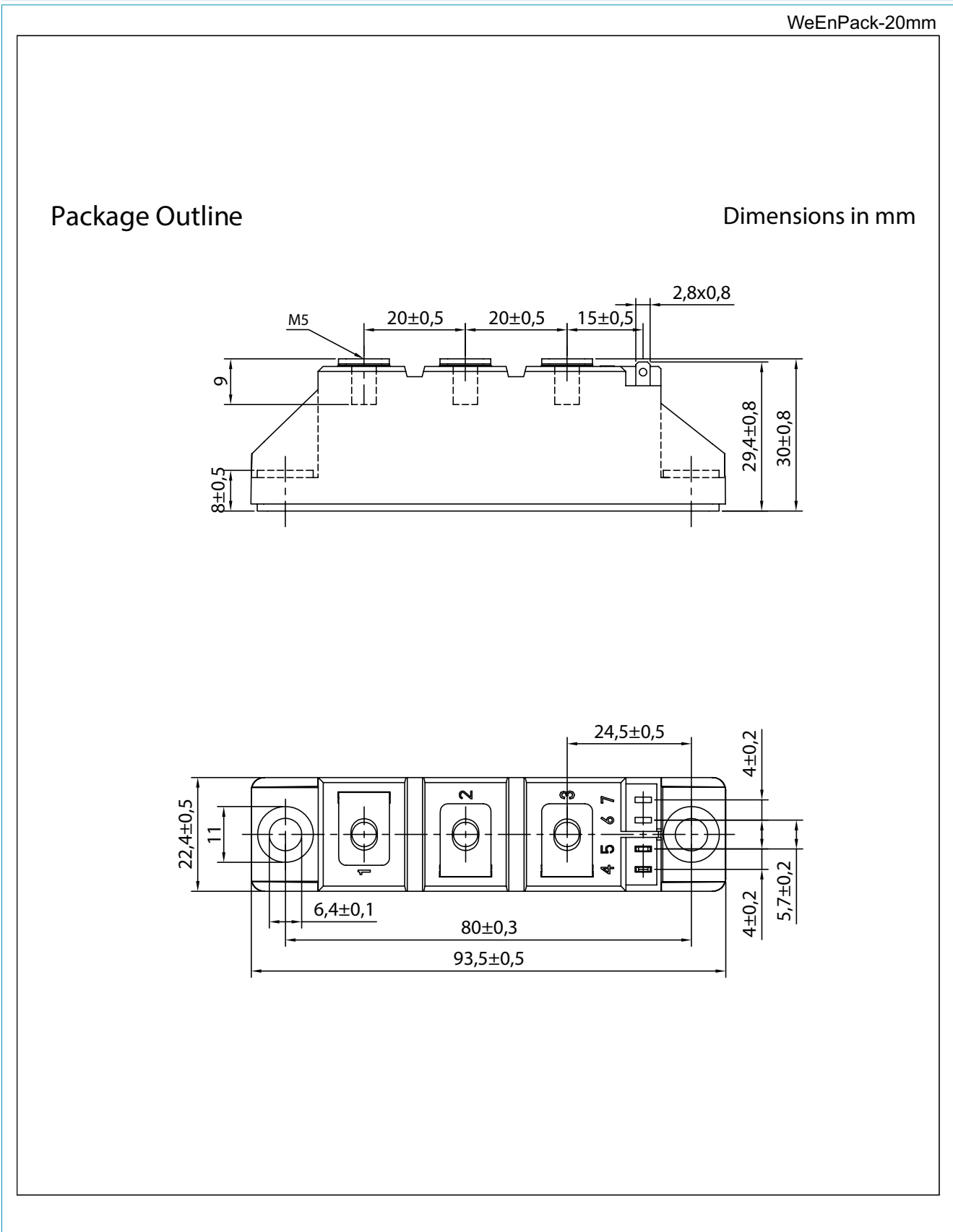
**Fig. 9. Gate voltage as a function of gate current**



$V_o = 0.889 \text{ V}$ ;  $R_s = 0.0030 \Omega$   
 (1)  $T_J = 150^\circ\text{C}$ ; typical values  
 (2)  $T_J = 150^\circ\text{C}$ ; maximum values  
 (3)  $T_J = 25^\circ\text{C}$ ; maximum values

**Fig. 10. Diode forward current as a function of forward voltage**

12. Package outline





## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
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14. Contents

1. General description..... 1

2. Features and benefits ..... 1

3. Applications ..... 1

4. Quick reference data..... 1

5. Pinning information..... 2

6. Ordering information..... 2

7. Marking..... 2

8. Limiting values ..... 3

9. Thermal characteristics ..... 5

10. Package characteristics..... 5

11. Characteristics..... 6

12. Package outline ..... 8

13. Legal information ..... 9

14. Contents ..... 11

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Date of release: 20 November 2024